ABSTRACT OF THE DISCLOSURE

SURFACE MOUNT TYPE ELECTRONIC COMPONENTS

Provided is a surface mount type electronic component which is obtained by molding a liquid crystalline polymer composition comprising: 100 parts by weight of a wholly aromatic liquid crystalline polymer having a crystalline melting temperature of 310-410°C, and 5-100 parts by weight of a glass fiber having a number average diameter of 4-8μm and a number average length of 100-200μm, wherein the LCP composition has a deflection temperature under load (DTUL) of 280-360°C.

No Figure

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